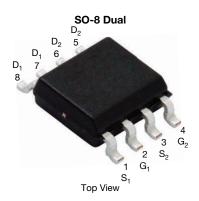


Automotive Dual P-Channel 30 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	-30			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -10 \text{ V}$	0.075			
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.145			
I _D (A) per leg	-5			
Configuration	Dual			

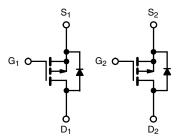
FEATURES

- TrenchFET® Power MOSFET
- 100 % R_q and UIS tested
- AEC-Q101 qualified c
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE



P-Channel MOSFET P-Channel MOSFET

ORDERING INFORMATION	
Package	SO-8
Lead (Pb)-free and halogen-free	SQ4937EY (for detailed order number please see www.vishay.com/doc?79771)

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	-30	V
Gate-source voltage		V _{GS}	± 20	
Continuous drain current	T _C = 25 °C		-5	
	T _C = 125 °C	- I _D	-3	
Continuous source current (diode conduction)		I _S	-3	А
Pulsed drain current ^a		I _{DM}	-20	
Single pulse avalanche current	1 0.1 ml 1	l _{AS}	-10	
Single pulse avalanche energy	L = 0.1 mH	E _{AS}	5	mJ
Maximum power dissipation ^a	T _C = 25 °C	D	3.3	w
	T _C = 125 °C	P_{D}	1.1	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-ambient PC	B mount b R _{thJA}	110	°C/W			
Junction-to-foot (drain)	R _{thJF}	45	C/VV			

Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. When mounted on 1" square PCB (FR-4 material)
- c. Parametric verification ongoing

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static	•						
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		- 30	-	-	V
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$		- 1.5	- 2.0	- 2.5	V
Gate-source leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nΑ
		V _{GS} = 0 V	V _{DS} = - 30 V	-	-	- 1.0	
Zero gate voltage drain current	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = - 30 V, T _J = 125 °C	-	-	- 50	μΑ
		$V_{GS} = 0 V$	V _{DS} = - 30 V, T _J = 175 °C	-	-	- 150	
On-state drain current ^a	I _{D(on)}	V _{GS} = - 10 V	V _{DS} ≤ - 5 V	- 15	-	-	Α
		V _{GS} = - 10 V	I _D = - 3.9 A	-	0.056	0.075	
Drain acuras an atata registance 3		V _{GS} = - 10 V	I _D = - 3.9 A, T _J = 125 °C	-	-	0.109	Ω
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = - 10 V	I _D = - 3.9 A, T _J = 175 °C	-	-	0.127	
		V _{GS} = - 4.5 V	I _D = - 2 A	-	0.119	0.145	
Forward transconductance b	9 _{fs}	V _{DS} =	V _{DS} = - 15 V, I _D = - 3.9 A		6	-	S
Dynamic ^b		•					
Input capacitance	C _{iss}			-	384	480	
Output capacitance	C _{oss}	$V_{GS} = 0 V$	$V_{DS} = -25 \text{ V, f} = 1 \text{ MHz}$	-	84	105	pF
Reverse transfer capacitance	C _{rss}			-	56	70	
Total gate charge ^c	Qg			-	9.5	15	
Gate-source charge ^c	Q _{gs}	V _{GS} = - 10 V	$V_{DS} = -15 \text{ V}, I_{D} = -4.9 \text{ A}$	-	1.7	-	nC
Gate-drain charge ^c	Q_{gd}			-	2.3	-	
Gate resistance	R _g		f = 1 MHz		-	10.5	Ω
Turn-on delay time ^c	t _{d(on)}			-	6	9	
Rise time ^c	t _r	$V_{DD} = -15 \text{ V}, R_L = 15 \Omega$ $I_D \cong -1 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		-	8	12	- ns
Turn-off delay time ^c	t _{d(off)}			-	15	23	
Fall time ^c	t _f			-	8	12	
Source-Drain Diode Ratings and Char	acteristics ^b						
Pulsed current ^a	I _{SM}			-	-	- 20	Α
Forward voltage	V _{SD}	I _F = - 3 A, V _{GS} = 0 V		_	- 0.85	- 1.2	V

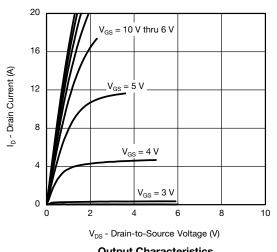
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

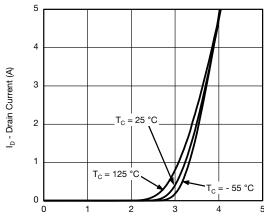
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



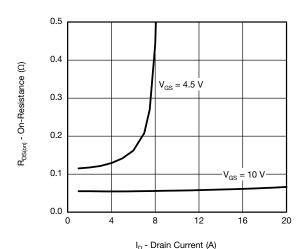
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



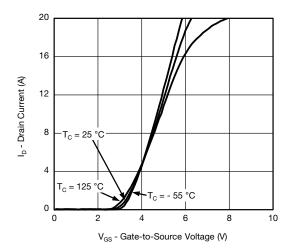
Output Characteristics



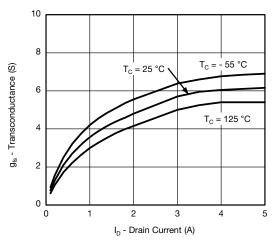
V_{GS} - Gate-to-Source Voltage (V) **Transfer Characteristics**



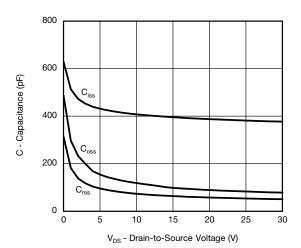
On-Resistance vs. Drain Current



Transfer Characteristics



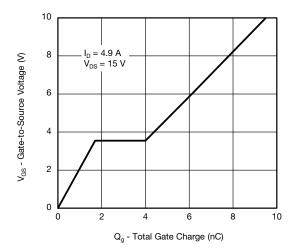
Transconductance



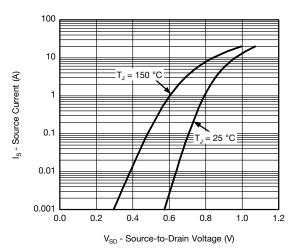
Capacitance



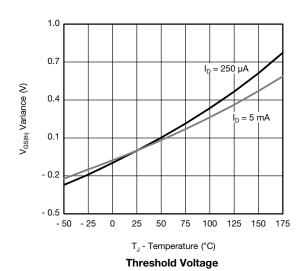
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

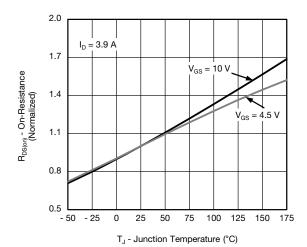


Gate Charge

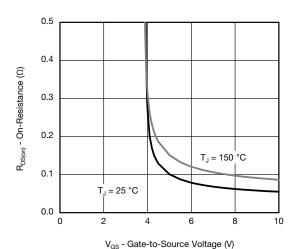


Source Drain Diode Forward Voltage

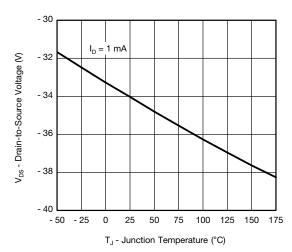




On-Resistance vs. Junction Temperature

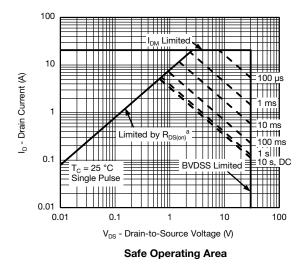


On-Resistance vs. Gate-to-Source Voltage



Drain Source Breakdown vs. Junction Temperature

THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)

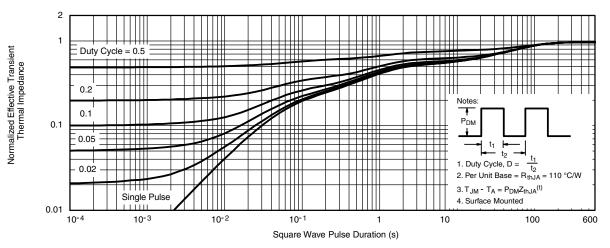


Note

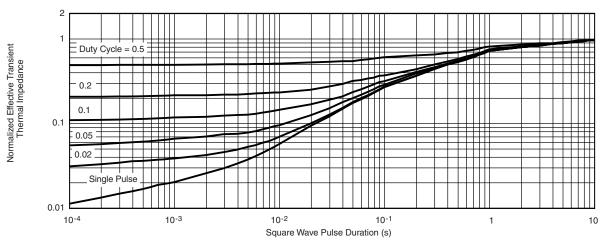
a. $V_{GS} > \mbox{minimum} \ V_{GS}$ at which $R_{DS(on)}$ is specified



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

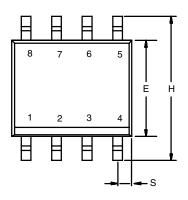
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C)

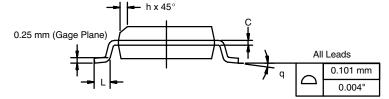
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIMETERS		INC	HES	
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I. 11-Sep-06					

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOT

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